



NiCr Thin Film, Top-Contact Resistor



Product may not be to scale

The SFN series resistor chips offer a combination of nichrome stability, good power rating and small size.

The SFNs are manufactured using Vishay Electro-Films (EFI) sophisticated thin film equipment and manufacturing technology. The SFNs are 100 % electrically tested and visually inspected to MIL-STD-883, method 2032, class H or class K.

FEATURES

- · Wire bondable
- Chip size: 0.020" square
- Case: 0202
- Resistance range: 20 Ω to 510 k Ω
- · Resistor material: Nichrome
- · Oxidized silicon substrate
- 125 mW power
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>



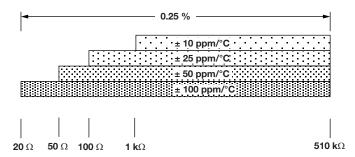
APPLICATIONS

Vishay EFI SFN resistor chips are widely used in hybrid packages where space is limited. Designed with capacity to handle substantial power loads, they also have the benefit of nichrome stability.

Recommended for hermetic environments where die is not exposed to moisture.

TEMPERATURE COEFFICIENT OF RESISTANCE, VALUES, AND TOLERANCES		
PARAMETER	VALUE	UNIT
Total Resistance Range	20 to 510K	Ω
Standard Tolerances	± 0.25	%
TCR	± 10, ± 25, ± 50, ± 100, ± 250	ppm/°C

Tightest Standard Tolerance Available



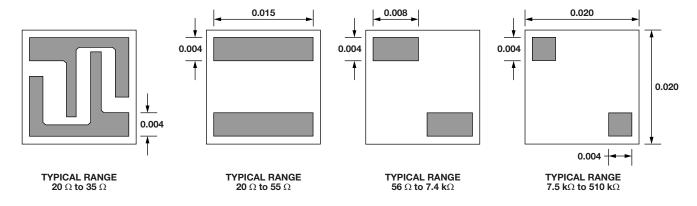
STANDARD ELECTRICAL SPECIFICATIONS		
PARAMETER	VALUE	UNIT
Noise, MIL-STD-202, Method 308 100 Ω to 250 k Ω < 100 Ω or > 251 k Ω	-35 typ. -20 typ.	dB
Stability, 1000 h, +125 °C, 50 mW	± 0.25 max. Δ <i>R/R</i>	%
Operating Temperature Range	-55 to +125	°C
Thermal Shock, MIL-STD-202, Method 107, Test Condition F	± 0.25 max. Δ <i>R</i> / <i>R</i>	%
High Temperature Exposure, +150 °C, 100 h	± 0.5 max. Δ <i>R/R</i>	%
Dielectric Voltage Breakdown	200	V
Insulation Resistance	10 ¹² min.	Ω
Operating Voltage	100 max.	V
DC Power Rating at +70 °C (Derated to Zero at +175 °C)	0.125	W
5 x Rated Power Short-Time Overload, +25 °C, 5 s	± 0.25 max. Δ <i>R/R</i>	%

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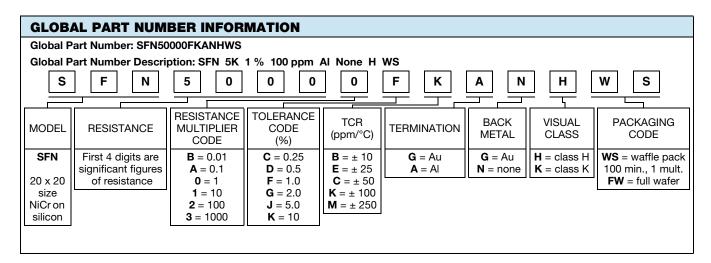
Vishay Electro-Films

DIMENSIONS in inches



SCHEMATIC

MECHANICAL SPECIFICATIONS		
PARAMETER	VALUE	
Chip Thickness	0.010" ± 0.002" (0.254 mm ± 0.05 mm)	
Chip Size	0.020" x 0.020" ± 0.003" (0.51 mm x 0.51 mm ± 0.076 mm)	
Chip Substrate Material	Oxidized silicon, 10 kÅ minimum SiO ₂	
Resistor Material	Nichrome (passivation optional)	
Bonding Pad Size	0.004" x 0.004" (0.10 mm x 0.10 mm)	
Number of Pads	2	
Pad Material	15 kÅ minimum gold (Al optional)	
Backing	None, lapped semiconductor silicon (Au back optional)	





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